

APPLICATION DATA SHEET

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22204

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Application Information:

Title of Invention: SOLDER BALL, METHOD OF MAKING THE SAME, AND
METHOD OF MAKING SEMICONDUCTOR INTERCONNECT
STRUCTURE

Application Type: regular, utility

Attorney Docket Number: 743421-82

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as our attorney(s) or agent(s) to prosecute the application identified above, and to transact
all business in the United States Patent and Trademark Office connected therewith.

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